Product Specification [产品规格书]:	ISSUED BY: Engineering Dept	
Subject [主题]: 0.60mm Pitch 0600 Series Connector Specification	Date Issued	2013/11/19
	Date Revised	2016/03/21

This specification is referred to the 0.60mm series IDC connector

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【1.适用范围 Scope】

此种规格包括 0.60mm Pitch 0600 Series 连接器规格说明.

This Specification Covers the 0.60mm Pitch 0600 Series Connector Specification.

【2.规格与料号 Spec and Part number】

规格内容 Specification	产品料号 Production No.	产品图示 Picture of Product
胶壳/Housing	0600HI-XX-XXXX	NONE
针座/Wafer	0600WRS-XX-XXXX	NONE

【3.材质与表面处理 Disposal of Material and surface】

规格内容 Specification		材 质 Materials	表面处理 Disposal of Surface
端子/Terminal		磷铜/Phosphor Bronze	Tin Plated: Over 70μ″ .Nickel: Over 30μ″ Gold Plated : Gold Flash″ ~3μ″ . Nickel : over 30μ″
胶壳/Housing		LCP	UL 94V-0
针座/Wafer	Base	LCP	UL 94V-0
	PIN	磷铜/Phosphor Bronze	Tin Plated: Over 70μ″ .Nickel: Over 30μ″ Gold Plated : Gold Flash″ ~3μ″ . Nickel : over 30μ″
	Solder tab	黄铜/Brass	Tin Plated: Over 70μ″ .Nickel: Over 30μ″ Gold Plated : Gold Flash″ ~3μ″ . Nickel : over 30μ″

（上述参数请以工程图为准/Please Refer to the Project drawing for the above Specification）

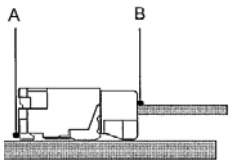
【4. 额定等级 Ratings and applicable wires】

项 目【Item】	规 格【Standard】	
额定电压 Rated Voltage (Max.)	30V	[AC/DC]
额定电流 Rated Current (Max.)	0.2A	
使用温度范围 Ambient temperature Range	-25℃~+85℃	
适用线径 Applicable wire insulation O.D	34 AWG ~36 AWG Insulation O.D. 0.29mm(Max.)	

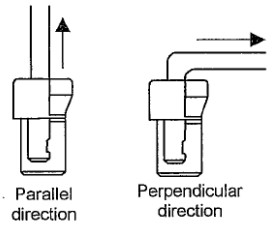
【*升温时含端子.Including terminal temperature rise.

【5.性能 PERFORMANCE】

5-1. 电气的性能 Electrical Performance.

项 目 【Item】		条 件 【Test Condition】	规 格 【Requirement】
5-1-1	接触阻抗 Contact Resistance	公母配合,开放电压 20mV 以下,电流 10mA 检测连接器 A~B 区. Mate connectors, measure by dry circuit, 20mV MAX, 10mA. (Based upon EIA-364-06A). 	Initial: 30 milliohms Max. After Test: 50 milliohms Max.
5-1-2	绝缘阻抗 Insulation Resistance	公母配合,在相邻端子,端子与地片之间,使用 100V 的直流电,检测连接器. Mate connectors, apply 100V DC between adjacent terminal or ground. (Based upon EIA-364-21B / MIL-STD-202 Method 302 Cond.B)	100 Megohms Min.
5-1-3	耐电压 Dielectric Strength	公母配合,在相邻端子,端子与地片之间,使用 200V 的交流电 1 分锺,检测连接器. Mate connectors, apply 200V AC for 1 minute between adjacent terminal or ground. (Based upon EIA-364-20A / MIL-STD-202 Method 301)	不出现中断等情况 No Breakdown and Flashover
5-1-4	铆线后端子接触阻抗 Contact resistance on crimped portion	铆线后之端子,开放电压 20mV 以下,电流 10mA 检测连接器. Crimp the applicable wire on to the terminal measure by dry circuit 20mV MAX, 10mA.	20 milliohms Max.

5-2. 机械的性能 Mechanical Performance.

项 目 【Item】		条 件 【Test Condition】	规 格 【Requirement】	
5-2-1	插拔力 Insertion & withdraw Force	以每分锺 25.4±3mm 的速率插入和拔出. Insert and withdraw Connectors at the speed rate of 25.4±3mm/minute.	参照第 6 项 Refer to paragraph 6	
5-2-2	线材保持力 Wire Retention Force	以每分 25±3mm 的速率,將线材從 Housing 拔出的力量. Apply axial pull out force at the speed rate of 25±3mm/minute on the Pull Out Force Axial direction.	平行方向 parallel	垂直方向 perpendicular
			3N {0.30kgf} Min. 36AWG	1N {0.10kgf} Min. 36AWG
5-2-3	Pin 针保持力 Pin Retention Force	以每分 25.4±3mm 的速率,將单 PIN 针从 Wafer 内轴向推出的力量. Apply axial push force at the speed rate of 25.4±3mm/minute.	0.784N {0.08kgf} Min.	

5-3. 环境性能及其它 Environmental Performance and Others.

项 目 【Item】		条 件 【Test Condition】	规 格 【Requirement】	
5-3-1	重复插拔 Repeated Insertion/ Withdrawal	以每分锺不超过 10 次的速率,将公母插拔 30 次. When mated up to 30 cycles repeatedly by the rate of 10 cycles per minute.	接触阻抗 Contact Resistance	50 milliohms Max.
5-3-2	温升测试 Temperature Rise	公母对插后,在通过额定电流下,所测定的温度. Carrying rated current load. (UL 1977)	温升测试 Temperature rise	30℃ Max.
5-3-3	振动测试 Vibration test	振幅: 1.5mm P-P 扫描时间: 10~55~10 HZ in 1 minute 持续时间: 每轴向 2 小时 Amplitude: 1.5mm P-P Sweep time: 10~55~10 HZ in 1 minute Duration: 2 hours in each X.Y.Z axials. (Based upon EIA-364-28B/MIL-STD-202 Method 213B Cond.A)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	50 milliohms Max.
			瞬断 Discontinuity	1 micro-second Max.
5-3-4	冲击测试 Shock test	在 X.Y.Z 上 6 个方向上,以 490m/s^2(50g 的力量)冲击下各 3 回，作用时间：6ms .490m/s^2{50G}, 3 strokes in each X.Y.Z. axes. 6 directiones Operation time:6ms (Based upon EIA-364-27B/MIL-STD-202 Method 213B Cond.A)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	50 milliohms Max.
			瞬断 Discontinuity	1 micro-second Max.
5-3-5	耐热性 Heat Resistance	85±2℃,96 hours. (Based upon MIL-STD-202 Method 108A Cond.A)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	50 milliohms Max.
5-3-6	耐寒性 Cold Resistance	-25±5℃,96 hours. (Based upon EIA-364-105)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	50 milliohms Max.

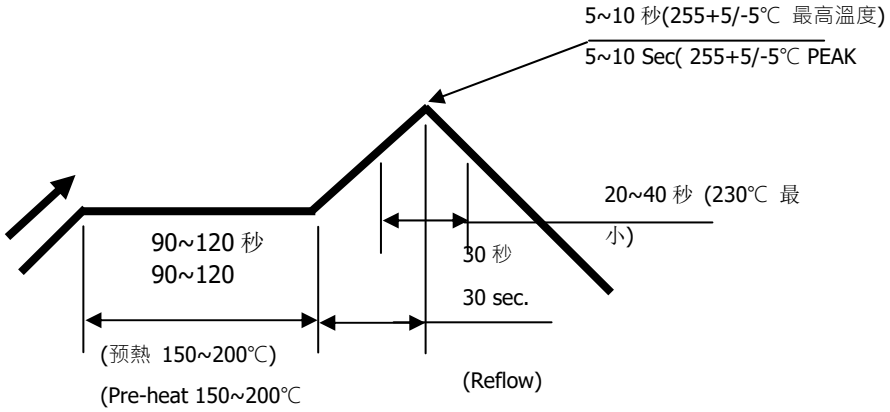
项 目 【Item】		条 件 【Test Condition】	规 格 【Requirement】	
5-3-7	耐湿性 Humidity	温度: 40±2℃ 湿度: 90~95%(RH) 持续时间: 96 hours Temperature: 40±2℃ Relative Humidity: 90~95% Duration: 96 hours (Based upon EIA-364-31A/MIL-STD-202 Method 103B Cond.B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	50 milliohms Max.
			耐电压 Dielectric Strength	Must meet 5-1-3
			绝缘阻抗 Insulation Resistance	50 Megohms Min.
5-3-8	温度变化 Temperature Cycling	从-25℃持续 30 分锺升至+85℃持续 30 分锺,循环 5 次. 5 cycles of: a) -25℃ 30 minutes. b) +85℃ 30 minutes. (Based upon EIA-364-32B)	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	50 milliohms Max.
5-3-9	盐水喷雾 Salt Spray	在温度 35±2℃,盐水浓度 5±1%下,盐水喷雾 24±1 小时. 24±1 hours exposure to a salt spray from the 5±1% solution at 35±2℃. (Based upon EIA-364-26A/MIL-STD-202 Method 101D Cond.B).	外观 Appearance	无异状 No Damage
			接触阻抗 Contact Resistance	50 milliohms Max.
5-3-10	焊锡附着性 Solder-ability	焊接时间: 3±0.5 秒. 焊接温度: 245±5℃. Soldering Time: 3±0.5second. Solder Temperature: 245±5℃. (Based upon EIA-364-52)	Solder Wetting	浸渍面积需 95%以上 95% of immersed area must show no voids, pin holes.
5-3-11	焊锡耐热性 Solder-Resistance	焊接时间: 5~10 秒. 焊接温度: 255+5/-0℃. Soldering time:5~10 sec solder. Temperature:255+5/-0℃. (Based upon EIA-364-56A)	外观 Appearance	无异状 No Damage

【6.综合插入力及拔出力 INSERTION/WITHDRAWAL FORCE】<Connector mating force>

PIN 数 No. of CKT	初次插入力(最大值) First Insertion (kgf Max.)	30 次拔出力(最小值) 30th Withdrawal (kgf Min.)	PIN 数 No. of CKT	初次插入力(最大值) First Insertion (kgf Max.)	30 次拔出力(最小值) 30th Withdrawal (kgf Min.)
02	1.0	0.05	09	1.7	0.20
03	1.1	0.05	10	1.8	0.25
04	1.2	0.10	11	1.9	0.25
05	1.3	0.10	12	2.0	0.30
06	1.4	0.15	13	2.1	0.30
07	1.5	0.15	14	2.2	0.35
08	1.6	0.20	15	2.3	0.35

注：以上插拔次数为 30 次　　Note：Insertion and Withdrawal for 30Cycles

【7. SMT 回流条件 SMT REFLOW CONDITION】



温度条件曲线图/ 基板上温度
TEMPERATURE CONDITION GRAPH/ (TEMPERATURE ON BOARD PATTERN SIDE)

注记：由于 P.C 板等焊接装置改变条件,所以请预先用自己的装置检查回流焊的条件.
Notes: Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C. boards, and so on.